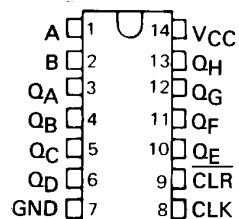


SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

MARCH 1974 — REVISED MARCH 1988

- Gated Serial Inputs
- Fully Buffered Clock and Serial Inputs
- Asynchronous Clear

SN54164, SN54LS164 . . . J OR W PACKAGE
SN74164 . . . N PACKAGE
SN74LS164 . . . D OR N PACKAGE
(TOP VIEW)



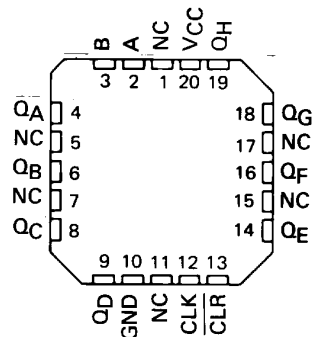
TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
'164	36 MHz	21 mW per bit
'LS164	36 MHz	10 mW per bit

description

These 8-bit shift registers feature gated serial inputs and an asynchronous clear. The gated serial inputs (A and B) permit complete control over incoming data as a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is high or low, but only information meeting the setup-time requirements will be entered. Clocking occurs on the low-to-high-level transition of the clock input. All inputs are diode-clamped to minimize transmission-line effects.

The SN54164 and SN54LS164 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN74164 and SN74LS164 are characterized for operation from 0°C to 70°C .

SN54LS164 . . . FK PACKAGE
(TOP VIEW)



NC — No internal connection

FUNCTION TABLE

INPUTS				OUTPUTS		
CLEAR	CLOCK	A	B	QA	QB . . . QH	
L	X	X	X	L	L	L
H	L	X	X	QA0	QB0	QH0
H	↑	H	H	H	QAn	QGn
H	↑	L	X	L	QAn	QGn
H	↑	X	L	L	QAn	QGn

H = high level (steady state), L = low level (steady state)

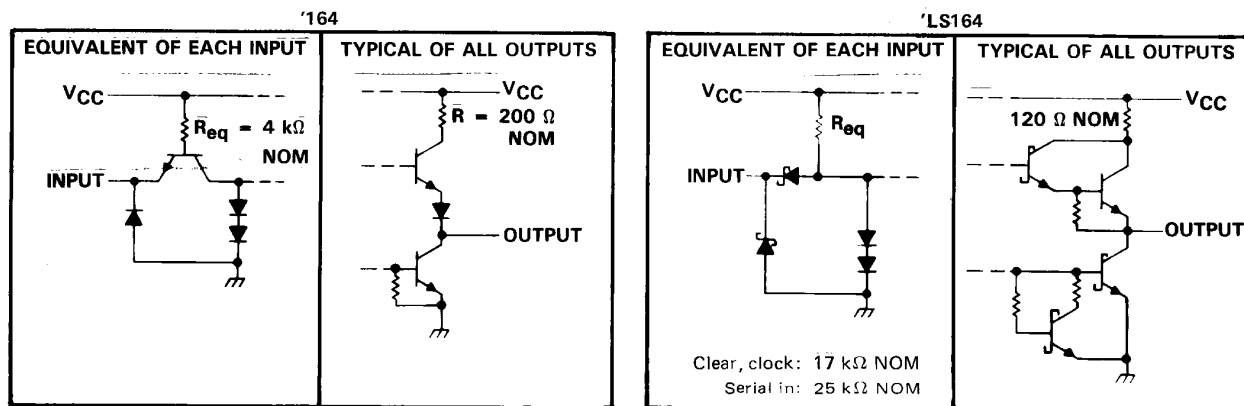
X = irrelevant (any input, including transitions)

↑ = transition from low to high level.

QA0, QB0, QH0 = the level of QA, QB, or QH, respectively, before the indicated steady-state input conditions were established.

QAn, QGn = the level of QA or QG before the most-recent ↑ transition of the clock; indicates a one-bit shift.

schematics of inputs and outputs

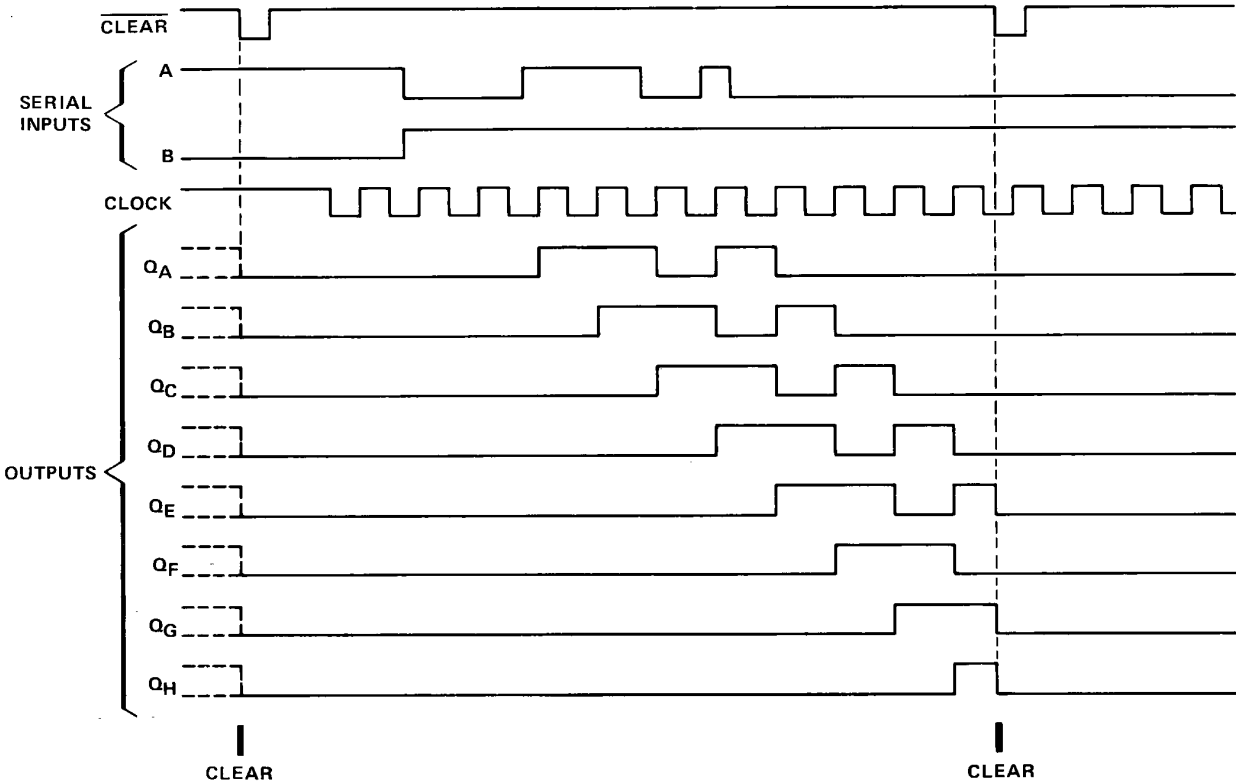


2

TTL Devices

SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

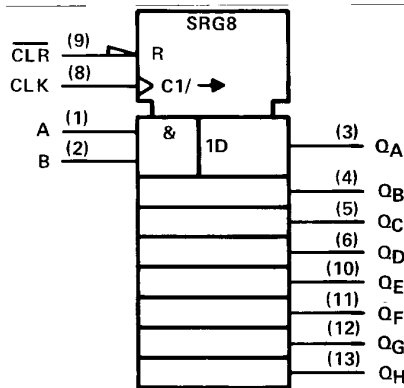
typical clear, shift, and clear sequences



2

TTL Devices

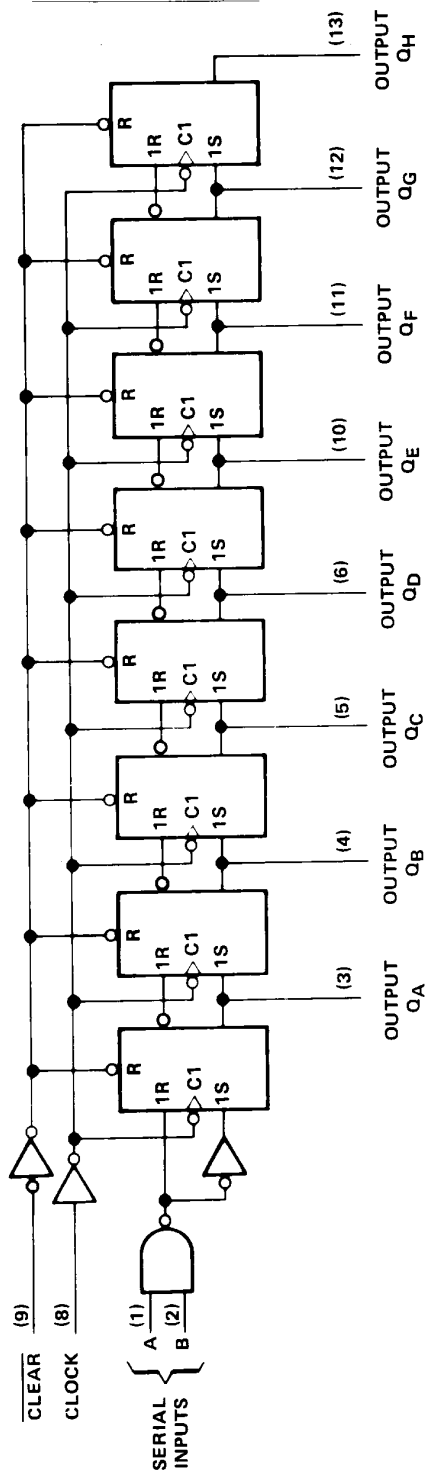
logic symbol†



†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTER

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

2

TTL Devices

SN54164, SN74164

8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54164	-55°C to 125°C
SN74164	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

	SN54164			SN74164			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			-400			-400	μ A
Low-level output current, I_{OL}			8			8	mA
Clock frequency, f_{clock}	0		25	0		25	MHz
Width of clock or clear input pulse, t_w	20			20			ns
Data setup time, t_{SU} (see Figure 1)	15			15			ns
Data setup time, t_{SU} (Clear Inactive) (see Figure 1)	20			20			ns
Data hold time, t_H (see Figure 1)	5			5			ns
Operating free-air temperature, T_A	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54164			SN74164			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH} High-level input voltage		2			2			V
V_{IL} Low-level input voltage				0.8			0.8	V
V_{IK} Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -12 \text{ mA}$			-1.5			-1.5	V
V_{OH} High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OH} = -400 \mu\text{A}$	2.4	3.2		2.4	3.2		V
V_{OL} Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 8 \text{ mA}$		0.2	0.4		0.2	0.4	V
I_I Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 5.5 \text{ V}$			1			1	mA
I_{IH} High-level input current	$V_{CC} = \text{MAX}, V_I = 2.4 \text{ V}$			40			40	μ A
I_{IL} Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$			-1.6			-1.6	mA
I_{OS} Short-circuit output current§	$V_{CC} = \text{MAX}$	-10		-27.5	-9		-27.5	mA
I_{CC} Supply current	$V_{CC} = \text{MAX}, V_I(\text{clock}) = 0.4 \text{ V}$			30			30	mA
	See Note 2 $V_I(\text{clock}) = 2.4 \text{ V}$			37			54	

† For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than two outputs should be shorted at a time.

NOTE 2: I_{CC} is measured with outputs open, serial inputs grounded, and a momentary ground, then 4.5 V, applied to clear.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max} Maximum clock frequency					MHz
t_{PHL} Propagation delay time, high-to-low-level Q outputs from clear input	$R_L = 800 \Omega,$ See Figure 1	$C_L = 15 \text{ pF}$	25	36	ns
		$C_L = 50 \text{ pF}$		24	
t_{PLH} Propagation delay time, low-to-high-level Q outputs from clock input	$R_L = 800 \Omega,$ See Figure 1	$C_L = 15 \text{ pF}$	8	17	ns
		$C_L = 50 \text{ pF}$	10	20	
t_{PHL} Propagation delay time, high-to-low-level Q outputs from the clock input	$R_L = 800 \Omega,$ See Figure 1	$C_L = 15 \text{ pF}$	10	21	ns
		$C_L = 50 \text{ pF}$	10	25	

SN54LS164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature range: SN54LS164	-55°C to 125°C
SN74LS164	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS164			SN74LS164			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
I_{OH}	High-level output current			-0.4			-0.4	mA
I_{OL}	Low-level output current			4			8	mA
f_{clock}	Clock frequency	0		25	0		25	MHz
t_w	Width of clock or clear input pulse	20			20			ns
t_{su}	Data setup time (See Figure 1)	15			15			ns
t_{su}	Clear inactive setup time (See Figure 1)	20			20			ns
t_h	Data hold time (See Figure 1)	5			5			ns
T_A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS164			SN74LS164			UNIT	
		MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V_{IK}	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.5			-1.5	V	
V_{OH}	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = \text{MAX}, I_{OH} = -0.4 \text{ mA}$	2.5	3.5		2.7	3.5		V	
V_{OL}	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = \text{MAX}$	$I_{OL} = 4 \text{ mA}$		0.25	0.4	$I_{OL} = 4 \text{ mA}$		0.25	0.4
		$I_{OL} = 8 \text{ mA}$				$I_{OL} = 8 \text{ mA}$		0.35	0.5
I_I	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$			0.1			0.1	mA	
I_{IH}	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$			20			20	μA	
I_{IL}	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$			-0.4			-0.4	mA	
I_{OS}	$V_{CC} = \text{MAX}$	-20		-100	-20		-100	mA	
I_{CC}	$V_{CC} = \text{MAX},$ See Note 3			16	27		16	27	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 3: I_{CC} is measured with outputs open, serial inputs grounded, the clock input at 2.4 V, and a momentary ground, then 4.5 V applied to clear.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$

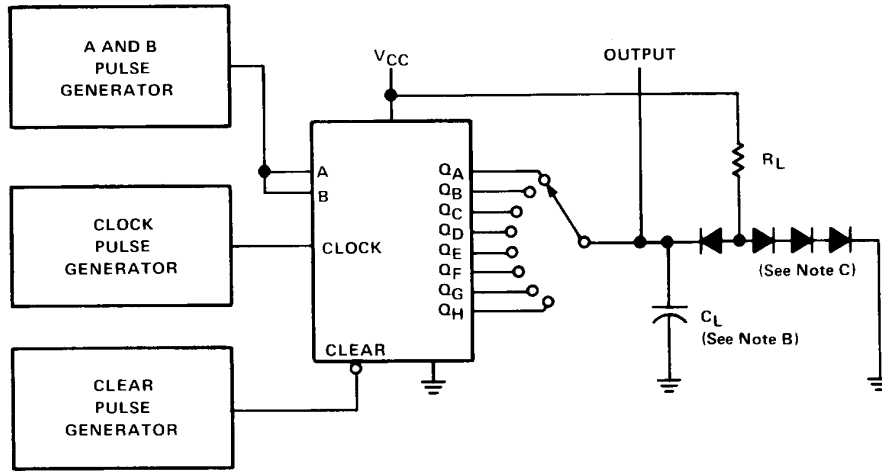
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max} Maximum clock frequency		25	36		MHz
t_{PHL} Propagation delay time, high-to-low-level Q outputs from clear input	$R_L = 2 \text{ k}\Omega, C_L = 15 \text{ pF},$		24	36	ns
t_{PLH} Propagation delay time, low-to-high-level Q outputs from clock input	See Figure 1		17	27	ns
t_{PHL} Propagation delay time, high-to-low-level Q outputs from clock input			21	32	ns

2

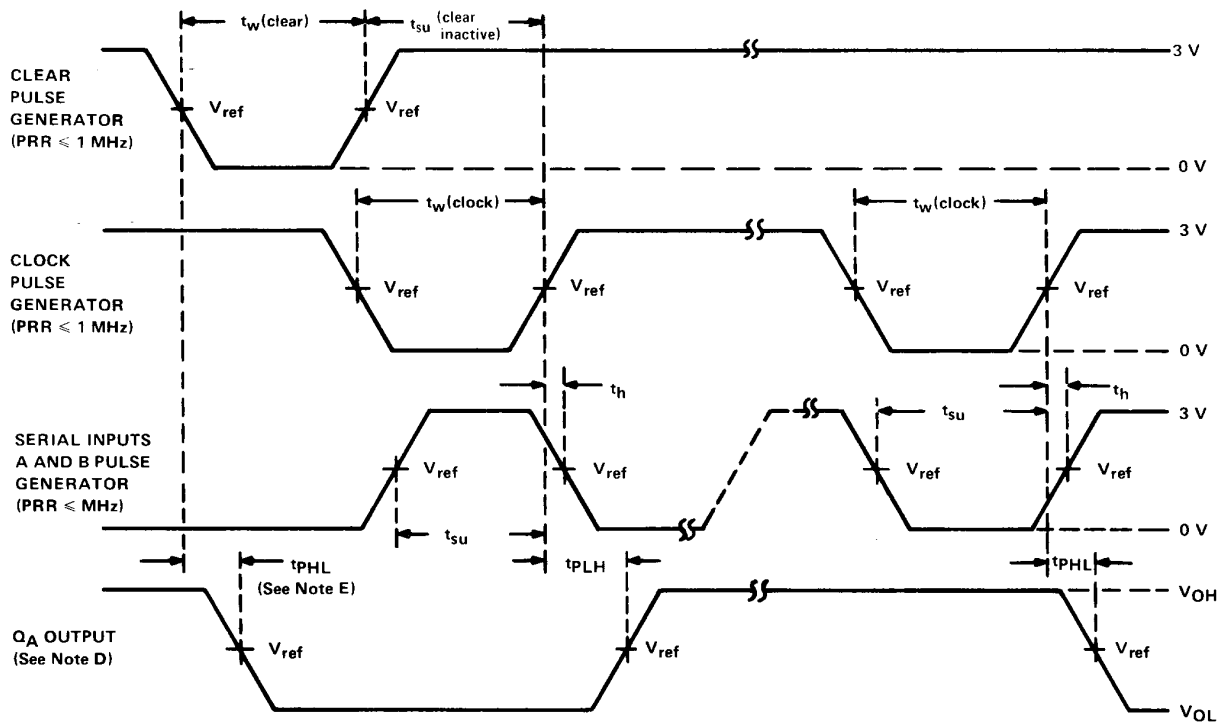
TTL Devices

SN54164, SN54LS164, SN74164, SN74LS164
8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

- NOTES: A. The pulse generators have the following characteristics: duty cyclé $\leq 50\%$, $Z_{out} \approx 50 \Omega$; for '164, $t_r \leq 10$ ns, $t_f \leq 10$ ns; and for 'LS164, $t_r \leq 15$ ns, $t_f \leq 6$ ns.
- B. C_L includes probe and jig capacitance.
- C. All diodes are 1N3064 or equivalent.
- D. Q_A output is illustrated. Relationship of serial input A and B data to other Q outputs is illustrated in the typical shift sequence.
- E. Outputs are set to the high level prior to the measurement of t_{PHL} from the clear input.
- F. For '164, $V_{ref} = 1.5$ V; for 'LS164, $V_{ref} = 1.3$ V.

FIGURE 1—SWITCHING TIMES

2

TTL Devices

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/00903BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30605BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30605BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30605SCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30605SCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30605SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30605SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS164J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS164J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN74164N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74164N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS164N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS164N	ACTIVE	PDIP	N	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
(RoHS)								
SN74LS164N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS164NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS164NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ54164W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54164W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS164J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS164J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS164W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS164W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

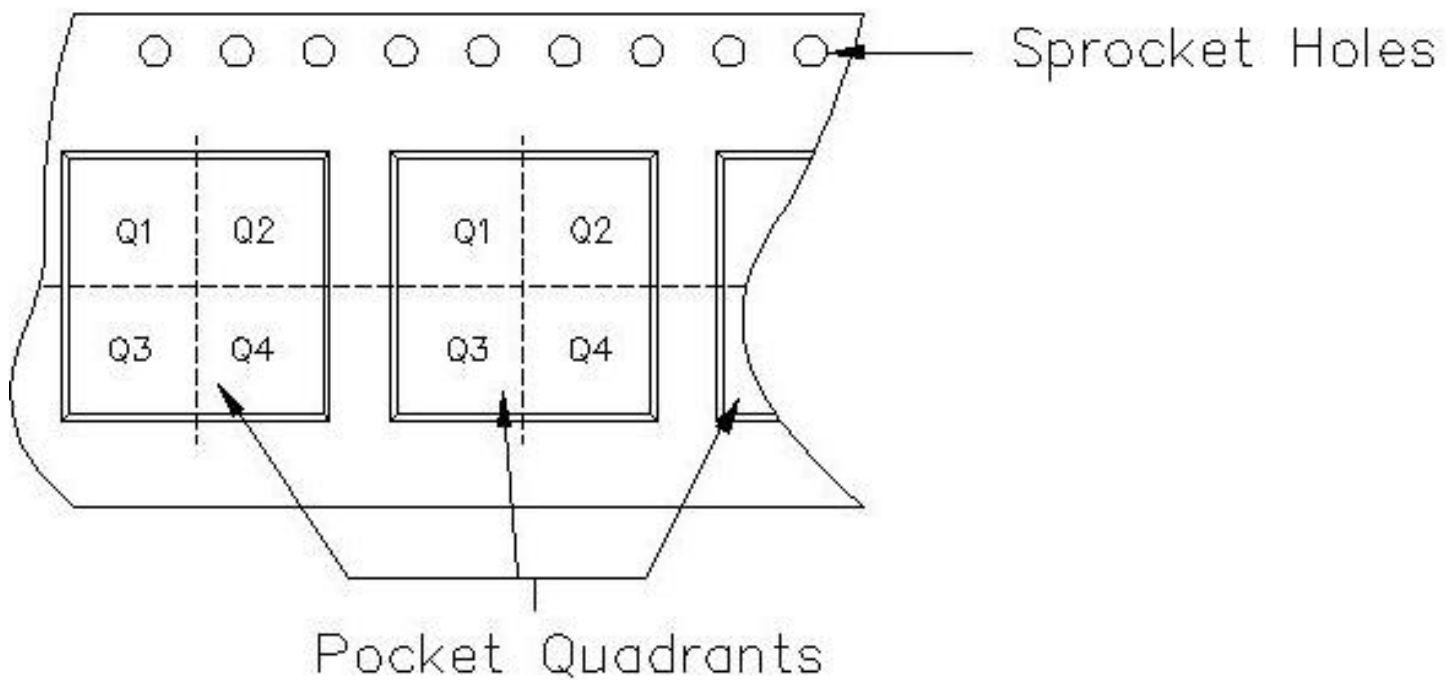
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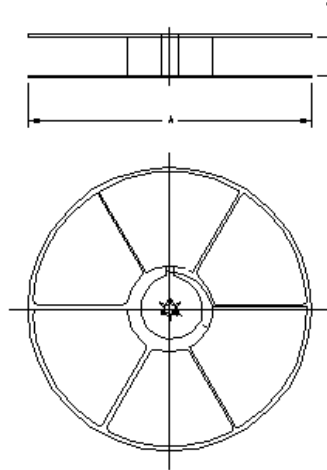
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



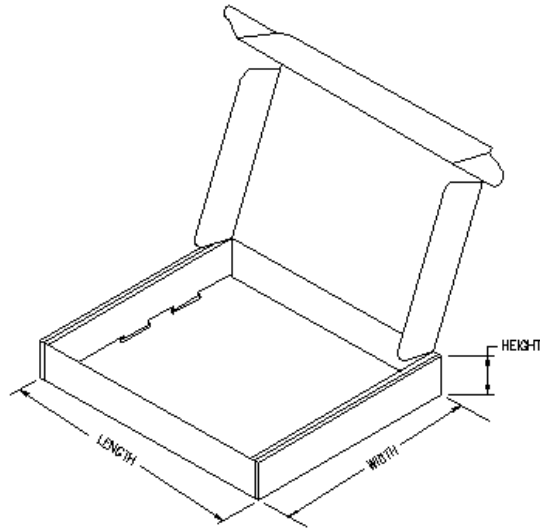
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS164DR	D	14	MLA	330	16	6.5	9.0	2.1	8	16	Q1
SN74LS164NSR	NS	14	MLA	330	16	8.2	10.5	2.5	12	16	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74LS164DR	D	14	MLA	342.9	336.6	28.58
SN74LS164NSR	NS	14	MLA	342.9	336.6	28.58



J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

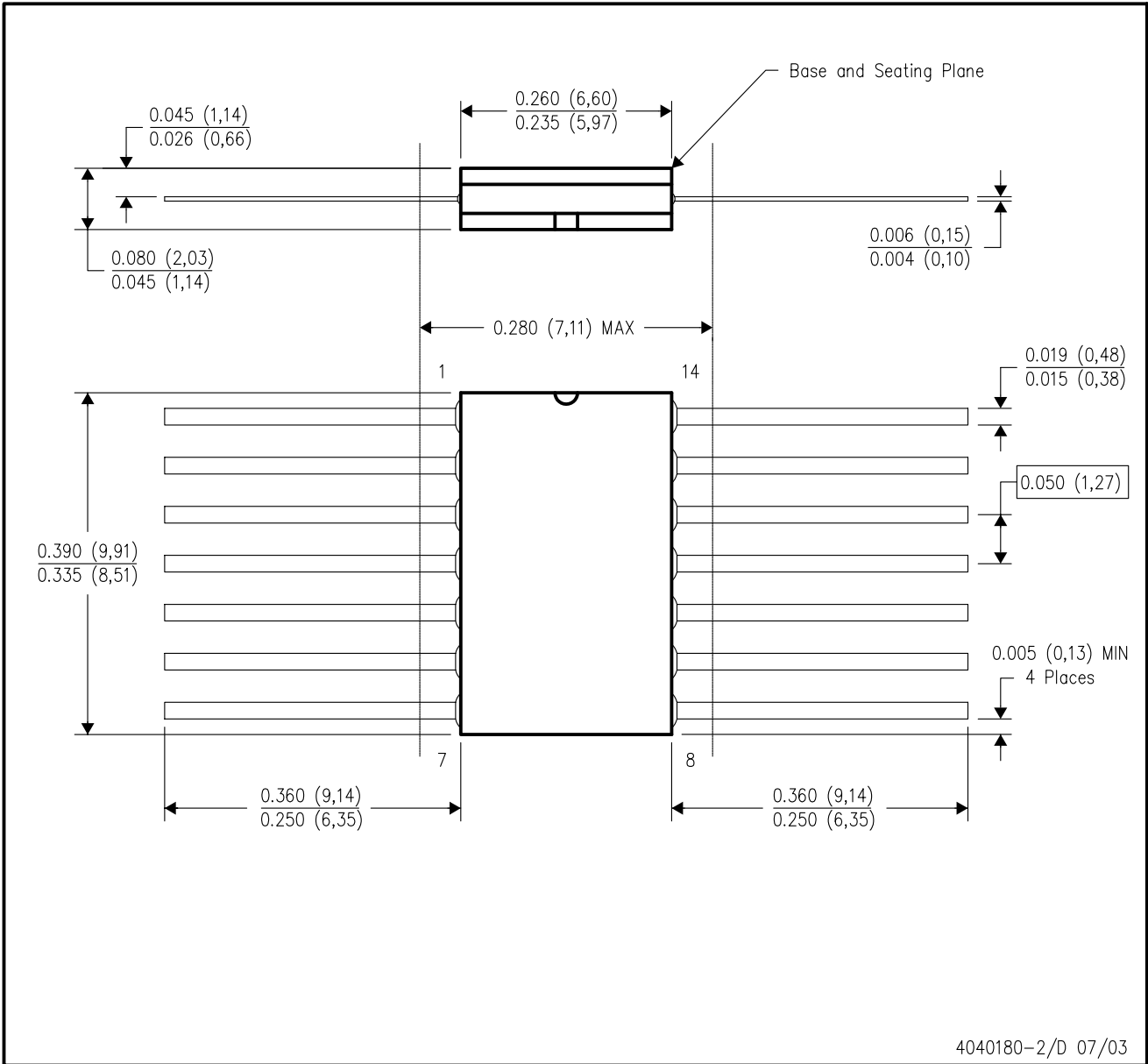


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/00903BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30605BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30605BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30605SCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30605SCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30605SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30605SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS164J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS164J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN74164N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74164N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS164N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS164N	ACTIVE	PDIP	N	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
(RoHS)								
SN74LS164N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS164NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS164NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS164NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS164NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ54164J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ54164W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54164W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS164J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS164J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS164W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS164W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS164DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS164NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS164DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS164NSR	SO	NS	14	2000	346.0	346.0	33.0

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

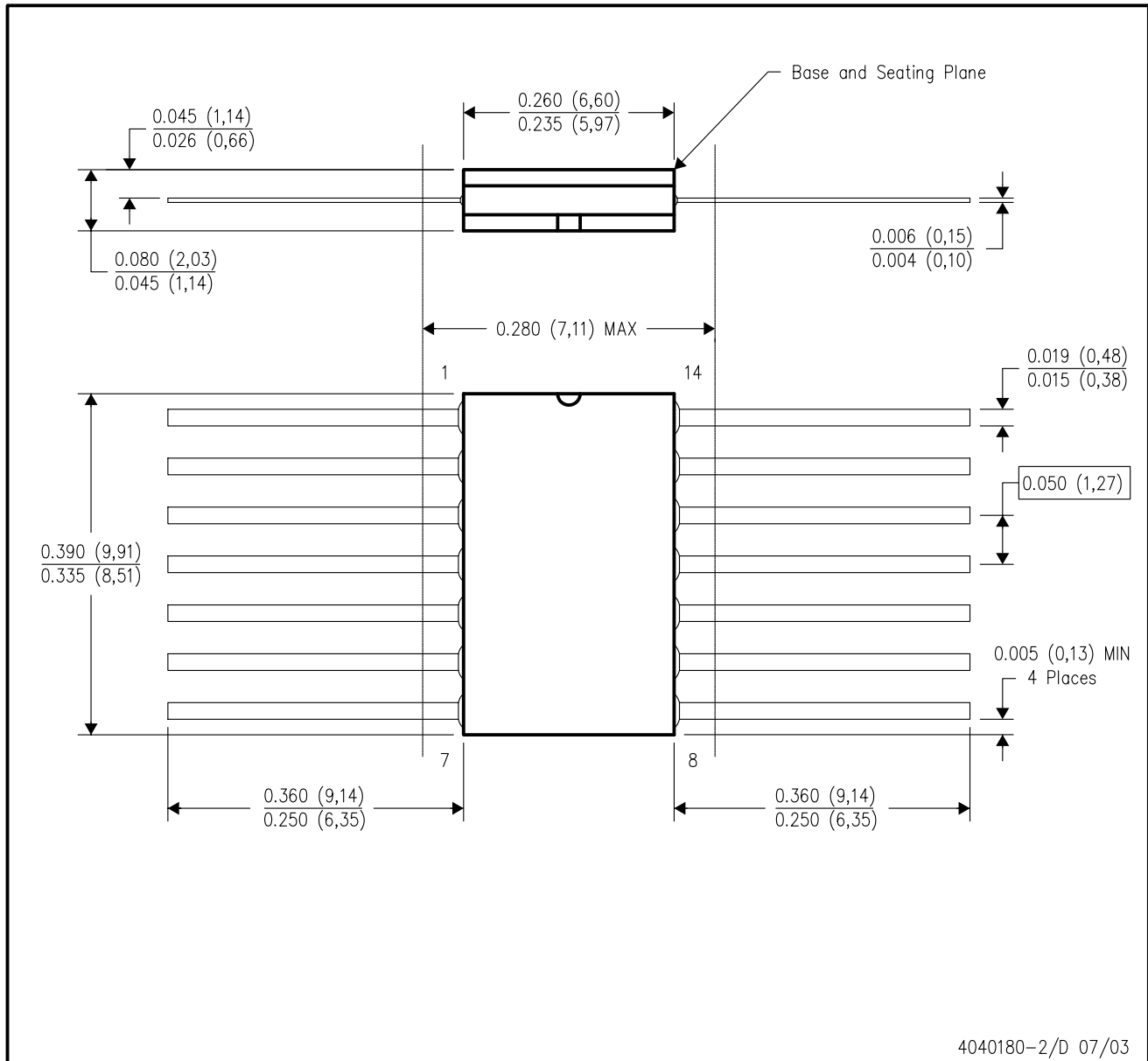
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

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